

**PATENT**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

LARRY ZHAO  
JEREMY MARTIN  
HARTMUT RUELKE

Confirmation No.: 7303

Examiner: Alexander G. Ghyka

Serial No.: 10/717,122

Group Art Unit: 2812

Filed: November 19, 2003

Att'y Docket: 2000.106900/DE0130

For: DIELECTRIC BARRIER LAYER FOR A  
COPPER METALLIZATION LAYER  
HAVING A VARYING SILICON  
CONCENTRATION ALONG ITS  
THICKNESS

Customer No.: 23720

**RESPONSE TO FINAL OFFICE ACTION DATED SEPTEMBER 13, 2007**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This paper is submitted in response to the Final Office Action dated September 13, 2007, for which the three-month date for response is December 13, 2007.

No fees are believed to be due in connection with the present paper. However, should any fees be required under 37 C.F.R. §§ 1.16 to 1.21, the Director is authorized to deduct such fees from Williams, Morgan & Amerson, P.C. Deposit Account No. 50-0786/2000.106900.

Reconsideration of the application in view of the following remarks is respectfully requested.